

Title (en)
PROCESS FOR DEFORMING A METAL PIECE

Publication
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Application
EP 89810916 A 19891205

Priority
US 28404688 A 19881214

Abstract (en)
[origin: EP0374094A1] In the process for producing thin metal parts, in particular thin sheets, preferably by mechanical hot forming, a metal piece (20) to be protected from corrosion is packed into a frame (22) and covered by two cover plates (28 and 28'); a parting compound (34) is interposed between metal piece (20) and cover (28,28'). The pack (36) thus produced is clamped together and welded along its edges. The stratified structure now present is mechanically formed, for example rolled down to a certain thickness. <??>The parting compound (34) is flowable at the forming temperature and forms a coherent parting layer between the cover plates (28,28') and the metal piece (20), which prevents a metallurgical binding between the two metals (20,28,28'). <??>After the hot forming the deformed pack is cooled down. Its edges are cut off and the envelope can be easily removed from the final product due to the parting compound intermediate layer, since, after cooling down, the parting compound is brittle and the metal surfaces poorly wettable. <??>Since the metal piece (20) is enclosed by an envelope (28,28',22), oxidation and/or other losses of quality of the metal piece (20) are prevented during the hot forming. <IMAGE>

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